

HVL385CM

Variable Capacitance Diode for VCO

REJ03G0035-0300 Rev.3.00 Mar 15, 2006

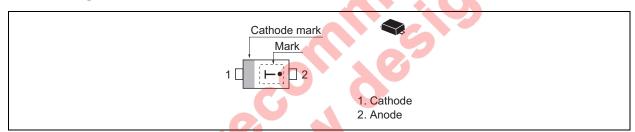
Features

- High capacitance ratio. (n = 2.43 min)
- Low series resistance. (rs = $0.75 \Omega \text{ max}$)
- Thin Extremely small Flat Lead Package (TEFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code	
HVL385CM	Т	TEFP	PUSF0002ZA-A	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Electrical Characteristics

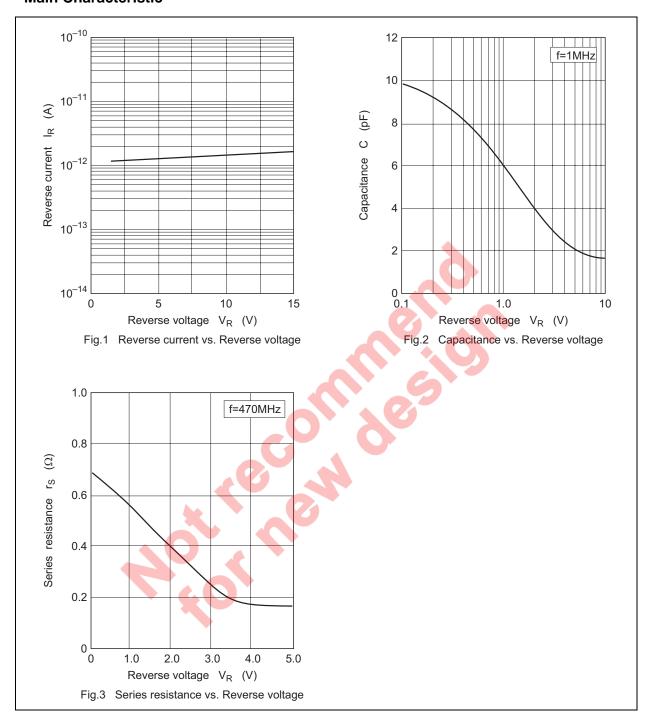
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 10 V
	I _{R2}	_	_	100		V _R = 10 V, Ta = 60°C
Capacitance	C _{0.5}	7.30	_	7.70	pF	$V_R = 0.5 \text{ V}, f = 1 \text{ MHz}$
	C _{2.5}	2.90	_	3.18		V _R = 2.5 V, f = 1 MHz
Capacitance ratio	n	2.43	_	2.57		C _{0.5} / C _{2.5}
Series resistance	r _S			0.75	Ω	V _R = 1 V, f = 470 MHz

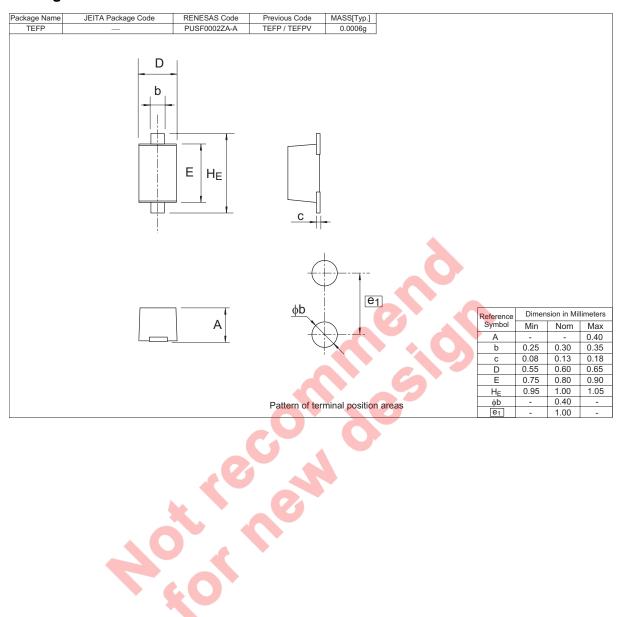
Note: For TEFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.



Main Characteristic



Package Dimensions



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